



PATENT ABSTRACTS OF JAPAN

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(54) MANUFACTURING METHOD OF
ANTI-STICKING MICROSTRUCTURE

(57) Abstract:

PROBLEM TO BE SOLVED: To provide a manufacturing method of an anti-sticking microstructure.

SOLUTION: In a micromachining process using a sacrificial layer 103 to manufacture a microstructure floating over a substrate, the manufacturing method of a microstructure includes a step of laminating an anti-sticking film 101 removable by dry etching before or after the lamination of the sacrificial layer. An adhesion phenomenon generated when the sacrificial layer is re-

moved by wet etching can be prevented. Dry etching is used for the anti-sticking film removal and a low-cost wet etching process can be used as it is for the sacrificial layer removal, so that the microstructure can be manufactured at a low cost.

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